

## C1808C563J5RACTM

Aliases (C1808C563J5RAC7025)

SMD Comm X7R, Ceramic, 0.056 uF, 5%, 50 VDC, X7R, SMD, MLCC, Temperature Stable, Class II, 1808, 2.9 mm



Click [here](#) for the 3D model.

### General Information

Series	SMD Comm X7R
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Class II
Features	Temperature Stable, Class II
RoHS	Yes
Termination	Tin
Marking	Yes
AEC-Q200	No
Typical Component Weight	41 mg
Shelf Life	78 Weeks
MSL	1

### Dimensions

Chip Size	1808
L	4.7mm +/-0.5mm
W	2mm +/-0.2mm
T	0.9mm +/-0.10mm
S	2.9mm MIN
B	0.6mm +/-0.35mm

### Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	2500

### Specifications

Capacitance	0.056 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	5%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1 kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	17.8571 GOhms

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